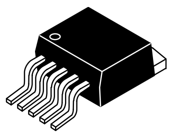

SCALE 1:1

D^{2}PAK5 / SMP5J
CASE 418AS
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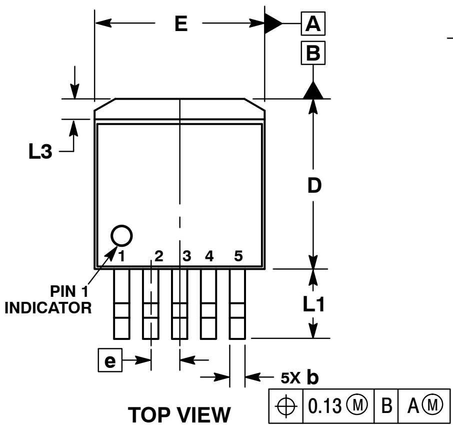
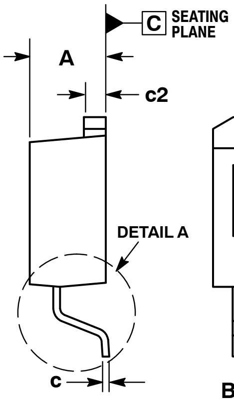
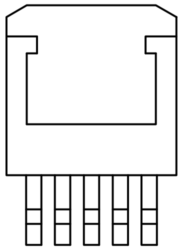


TOP VIEW



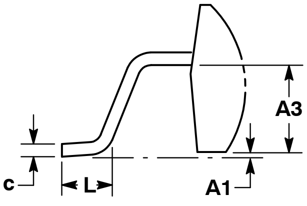
SIDE VIEW



BOTTOM VIEW

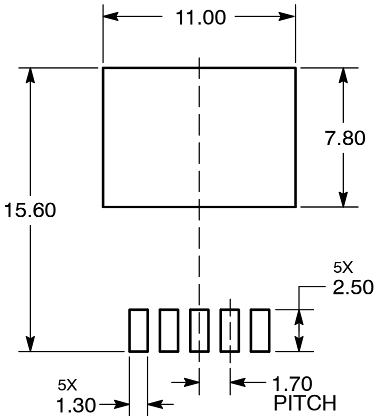
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 MILLIMETERS PER SIDE.
4. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. DATUMS A AND B ARE DETERMINED AT DATUM PLANE C.

	MILLIMETERS	
DIM	MIN	MAX
A	4.20	4.80
A1	0.00	0.30
A3	2.40	3.00
b	0.75	1.05
c	0.25	0.55
c2	1.10	1.50
D	9.50	10.30
E	9.80	10.20
e	1.70 BSC	
L	1.20	1.80
L1	3.80	4.40
L3	1.00	1.40



DETAIL A

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**D^{2}PAK5 / SMP5J**	**PAGE 1 OF 1**